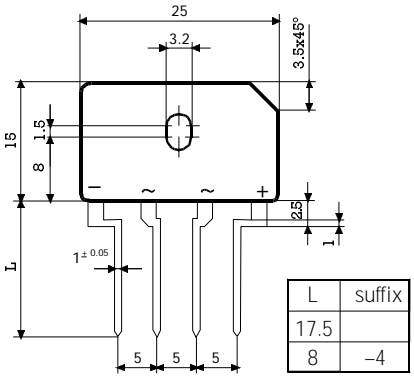
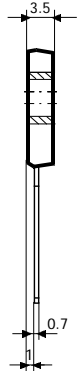



6 Amp. Glass Passivated Bridge Rectifier

<p>Dimensions in mm.</p>  <p>Mounting Instructions</p> <ul style="list-style-type: none"> High temperature soldering guaranteed: 260 °C – 10 sc. Recommended mounting torque: 8 Kg.cm. 	<p>Plastic Case</p> 	<p>Voltage 50 to 1000 V.</p> <p>Current 6.0 A.</p> 
<ul style="list-style-type: none"> Glass Passivated Junction Chips. UL recognized under component index file number E130180. Lead and polarity identifications. Case: Molded Plastic. Ideal for printed circuit board (P.C.B.). High surge current capability. The plastic material carries U/L recognition 94 V-O. 		

Maximum Ratings, according to IEC publication No. 134

		FBI6A 5M1	FBI6B 5M1	FBI6D 5M1	FBI6G 5M1	FBI6J 5M1	FBI6K 5M1	FBI6M 5M1
V_{RRM}	Peak recurrent reverse voltage (V)	50	100	200	400	600	800	1000
V_{RMS}	Maximum RMS voltage (V)	35	70	140	280	420	560	700
$I_{F(AV)}$	Max. Average forward current with heatsink without heatsink	6.0 A at 100 °C 3.0 A at 40 °C						
I_{FSM}	8.3 ms. peak forward surge current (Jedec Method)	175 A						
I^2t	Rating for fusing ($t < 8.3$ ms.)	127 A ² sec						
V_{DIS}	Dielectric strength (terminals to case, AC 1 min.)	1500 V						
T_j	Operating temperature range	– 55 to + 150 °C						
T_{stg}	Storage temperature range	– 55 to +150 °C						

Electrical Characteristics at Tamb = 25°C

V_F	Max. forward voltage drop per element at $I_F = 6$ A	1.0V
I_R	Max. reverse current per element at V_{RRM}	5 μ A
$R_{th(j-c)}$	MAXIMUM THERMAL RESISTANCE Junction-Case. With Heatsink.	2.2 °C/W
$R_{th(j-a)}$	Junction-Ambient. Without Heatsink.	22 °C/W



Characteristic Curves

